TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

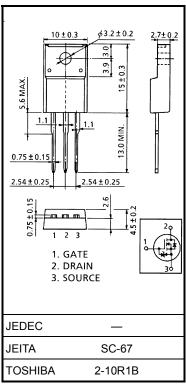
2SK3067

Chopper Regulator, DC–DC Converter and Motor Drive Applications

- Low drain-source ON resistance $: RDS (ON) = 4.2 \Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 1.7 \text{ S (typ.)}$
- Low leakage current $: IDSS = 100 \ \mu A \ (max) \ (VDS = 600 \ V)$
- Enhancement mode : $V_{th} = 2.0 \sim 4.0 V (V_{DS} = 10 V, I_D = 1 mA)$

Absolute Maximum Ratings (Ta = 25°C)

Charac	teristics	Symbol	Rating	Unit
Drain-source volta	ge	V _{DSS}	600	V
Drain-gate voltage	e (R _{GS} = 20 kΩ)	V _{DGR}	600	V
Gate-source voltage	ge	V _{GSS}	±30	V
Drain current	DC (Note 1)	I _D	2	А
	Pulse (t = 1 ms) (Note 1)	I _{DP}	5	A
	Pulse (t = 100 µs) (Note 1)	I _{DP}	8	A
Drain power dissipa	ation	PD	25	W
Single pulse avalar	nche energy (Note 2)	E _{AS}	93	mJ
Avalanche current		I _{AR}	2	А
Repetitive avalance	he energy (Note 3)	E _{AR}	2.5	mJ
Channel temperatu	ire	T _{ch}	150	°C
Storage temperatu	re range	T _{stg}	-55~150	°C



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Max	Unit
Thermal reverse, channel to case	R _{th (ch-c)}	5.0	°C / W
Thermal reverse, channel to ambient	R _{th (ch−a)}	62.5	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 41 mH, R_G = 25 Ω , I_{AR} = 2 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature.

This transistor is an electrostatic-sensitive device. Please handle with caution.

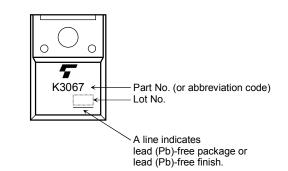
Electrical Characteristics (Ta = 25°C)

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_		±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	—	_	V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0		4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 1 A	_	4.2	5.0	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 1 A	0.8	1.7	_	S
Input capacitance C _{iss} Reverse transfer capacitance C _{rss}		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	380	_	pF
		C _{rss}		_	40	_	
Output capacitance		Coss		_	120	_	
Switching time	Rise time	tr	$V_{\text{GS}} \stackrel{10V}{_{0V}} \int I_{\text{D}} = 1A \\ R_{\text{L}} = 200\Omega \\ V_{\text{DD}} = 200V$	_	15	_	
	Turn-on time	t _{on}		_	25	_	20
	Fall time	tf		_	20	_	ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, t _w =10µs	- 80	80	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	9	_	
Gate-source charge		Q _{gs}	V _{DD} ≈ 480 V, V _{GS} = 10 V, I _D = 2 A		5	_	nC
Gate-drain ("miller") charge		Q _{gd}			4	_	

Source–Drain Ratings and Characteristics (Tc = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	2	А
Pulse drain reverse current (Note 1)	I _{DRP}	t = 1 ms	_	_	5	А
	IDRP	t = 100 μs	_	_	8	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 2 A, V _{GS} = 0 V	_	_	-1.5	V
Reverse recovery time	t _{rr}	I _{DR} = 2 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs	_	1000	—	ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs	_	5.0	_	μC

Marking



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